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PreAmok G
S. Zimmerman
8-2402

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of Applicants:

Beaman et al.

Serial No.: 09/921,867

Filed: August 3, 2001

For: HIGH DENSITY INTEGRATED CIRCUIT APPARATUS,
TEST PROBE AND METHODS OF USE THEREOF

Date: August 8, 2002

Group Art Unit: 3729

Examiner:

Docket No.: YOR919930028US6 GROUP 3700

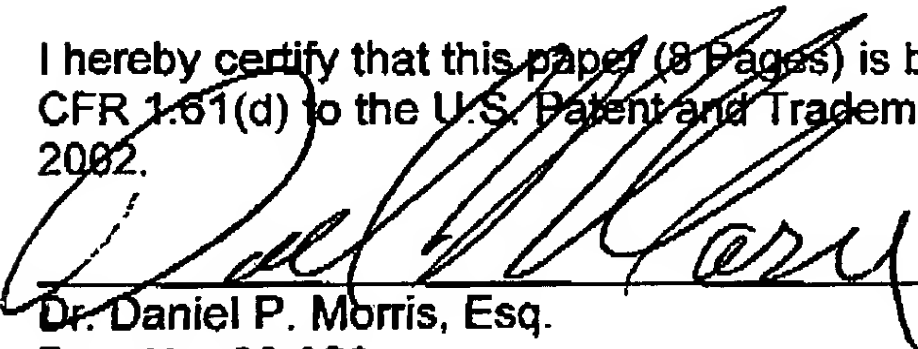
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EIGHT PRELIMINARY AMENDMENT

IN THE CLAIMS

Amended Claims:

372. (Amended) A structure, according to claim [336] 356, wherein:

the second substrate is a multi-layer interconnection substrate.

373. (Amended) A structure, according to claim [335] 356, wherein:

the elongated electrical conductor extending from the locations of the surface of
the first substrate comprises a wire.

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01 FC:103 360.00 CH

02 FC:102 84.00 CH

Serial No. 09/921,867

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